

ABSTRACT OF THE DISCLOSURE

An object of the present invention is to provide a leadless package type electronic part, the cost and the size of which can be reduced and which exhibits excellent reliability, an electronic part material for manufacturing the electronic parts, and a method therefor. The electronic part of a leadless package type includes a rectangular substrate having a plurality of external electrodes in the periphery thereof, an element part placed on the surface of the substrate while being electrically connected to the external electrodes, and molding resin for molding the element part onto the surface of the substrate, wherein the surface of the molding resin is formed to be flat, and each side surface of the molding resin and each side surface of the substrate have the same surface.